



PK744 (v1.0) May 29, 2015

100% Material Declaration Data Sheet Spartan®-6 Cu Wire TQ144 Package

Average Weight: 1.3109 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.013300	1.015%
	Silicon	7440-21-3	100.00	Main material	0.013300	
Die Attach Material					0.002254	0.172%
	Silver	7440-22-4	73.00	Main material	0.001645	
	Epoxy resin	trade secret	7.50	Main material	0.000169	
	Anhydride	trade secret	7.50	Main material	0.000169	
	2,6-Diglycidyl phenyl allyl ether oligomer	trade secret	3.00	Main material	0.000068	
	Epoxy resin	trade secret	3.00	Main material	0.000068	
	Epoxy resin modifier	trade secret	3.00	Main material	0.000068	
	Anhydride	trade secret	3.00	Main material	0.000068	
Copper Wire					0.000833	0.064%
	Cu	7440-50-8	98.25	Main material	0.000818	
	Pd	7440-05-3	1.75	Dopant	0.000015	
Mold Compound					1.107145	84.457%
	Epoxy Resin	Trade Secret	10.00	Epoxy Resin	0.110715	
	Phenol Resin	Trade Secret	5.00	Phenol Resin	0.055357	
	Silica(Amorphous) A	60676-86-0	74.00	Silica(Amorphous) A	0.819287	
	Silica(Amorphous) B	7631-86-9	10.00	Silica(Amorphous) B	0.110715	
Carbon Black	1333-86-4	1.00	Carbon Black	0.011071		
External Plating					0.014300	1.091%
	Tin (Sn)	7440-31-5	85.00	Main material	0.012155	
	Lead (Pb)	7439-92-1	15.00	Main material	0.002145	
Lead Frame					0.167068	12.745%
	Copper (Cu)	7440-50-8	91.964	Main material	0.153643	
	Nickel (Ni)	7440-02-0	3.088	Main material	0.005159	
	Silicon (Si)	7440-21-3	1.158	Main material	0.001935	
	Magnesium (Mg)	7439-95-4	0.290	Main material	0.000484	
	Silver (Ag)	7440-22-4	3.500	Main material	0.005847	

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Lead Frame Tape					0.006000	0.458%
	Polyimide	Trade secret	43.00		0.002580	
	Poly-ethylene-terephthalate	Trade secret	25.00		0.001500	
	NBR (Acrylonitrilebutadiene rubber)	Trade secret	12.00		0.000720	
	Bismaleimide	Trade secret	10.00		0.000600	
	Phenol resin	Trade secret	10.00		0.000600	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/29/15	1.0	Initial Xilinx release

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